Qmax Systems

Electronics Engineering Services

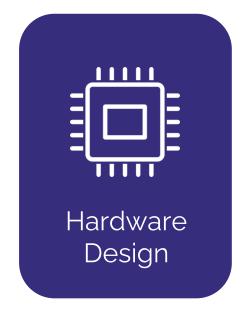


Qmax Introduction

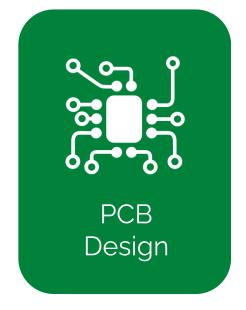
- An Electronics Engineering and R&D Services company
- Complete End to End Product Development
- R&D Team in Chennai, India, Sales office in the USA
- Strong Experience in working on Complex, Cutting Edge Technology
- Multi Domain Expertise Automotive / Aerospace / Industrial / Medical / Defence
- Incorporated in 2000



Services Offered



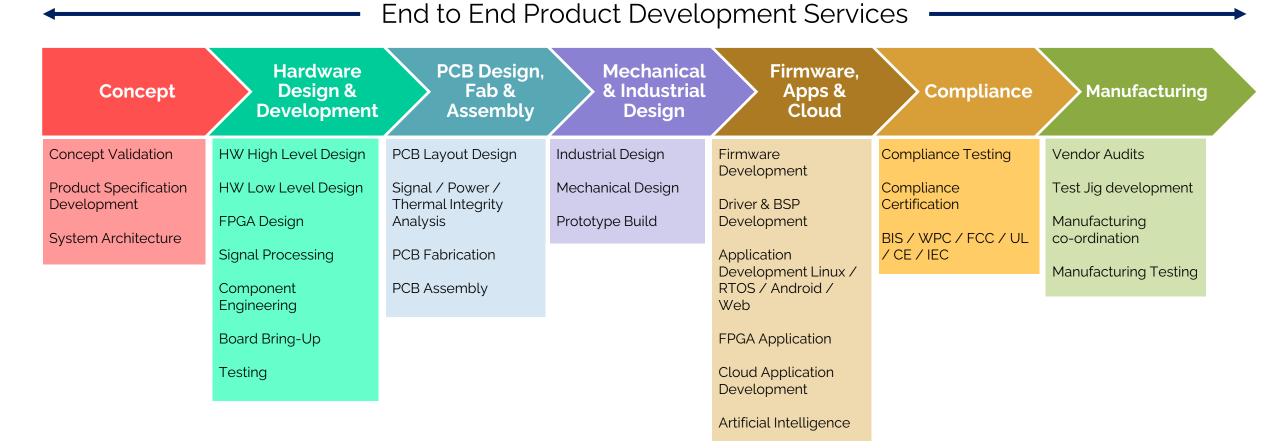








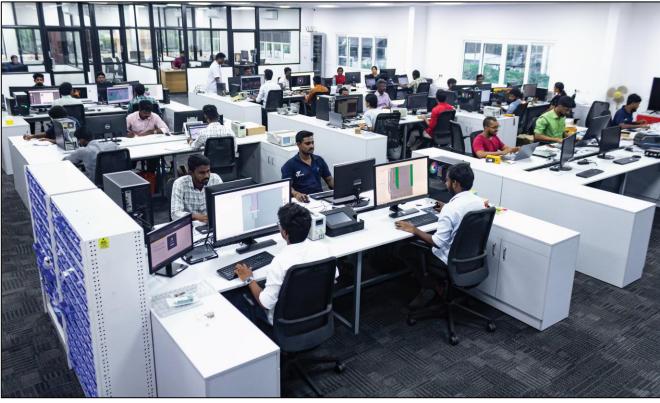
Design to Manufacturing





Infrastructure – Chennai HQ







Quality Assurance

- ISO 9001:2015 Certified Company
- Qmax Systems has established, documented, and implemented a Quality Management System.
- The system is maintained and continually improved using the quality policy, quality objectives, internal & external review results, analysis of data, corrective and preventive action and periodic management reviews.



CERTIFICATE OF REGISTRATION

This is to certify that the Management System of

Qmax Systems India Pvt Ltd

310-2A, Rukmani Nagar, 4th Street, Poonamallee, Chennai -600056, Tamil Nadu, India

has been assessed and registered by Veritas System Quality Certificates as conforming to the requirements of

ISO 9001:2015

Quality Management System

The Quality Management System is applicable to:

To Provide Electronics Design, Embedded Systems Development, Production & Engineering services as per customer requirements across Industries.

IAF/EA-NACE Code: 19-26.12

Certificate No: VSQC099-42100115 - R1

Initial Certificate Date : 23-07-2022 Re-certification due date: 22-07-2025 D. W.Mian

Authorised Signatory

Veritas System
Quality Certificates Issuing LLC

P.O. Box: 122982, Al Karama, Dubai United Arab Emirates.









This certificate remains valid while the holder maintains the management system in accordance with the standard(s) abov which will be periodically audited by Veritas System Quality Certificates Issuing LLC.

This certificate remains the property of Veritas System Quality Certificates Issuing LLC and must be returned on request. In the issuance of this certificate, Veritary System Quality Certificates Issuing LLC on liability to any party other than to be client, and then only in accordance with the agreed upon certification agreement. Validity of this certificate may be confirmed at www.veritasassurance.com, directly through QR code by usins any devise with correct information or email to adminificatemissassurance.com.





IP Protection and Data Security

- Non-Disclosure Agreements: NDAs with Employees, Vendors and Customers.
- Firewall & VPN: Secure network with firewall and VPN.
- Need-to-Know Access: Sensitive info accessible only to necessary individuals.
- Security Awareness: Regular employee training on data security and IP Protection.
- Access Control: Only authorized personnel can access premises.



Hardware Capabilities



Hardware Capabilities

- High-Speed Digital Designs
- Analog and Mixed Signal Designs
- Power Electronics
- RF Designs
- FPGA Based Designs



In-House Test Equipment

- Rohde & Schwarz Wideband Radio Communication Tester CMW-500
- Keysight Oscilloscopes
- Rigol Programmable Power Supplies
- Fluke Digital Multimeters
- Rigol Programmable Function Generators
- FLIR and Uni-T Thermal Cameras
- Uni-T IR Thermometers
- Fluke Temperature Logger
- Temperature Chambers
- Acoustic Testing Chamber
- Drop Test Chamber



Embedded Firmware Capabilities



Firmware Capabilities

	Embedded	OS	Apps & Cloud
Capabilities	 Bare Metal C , C_++ Boot loader OTA FW Upgrades Protocol Stack Low Power & Memory design Boot time optimisation Rich GUI Micro Python 	 RTOS Embedded Linux Device Drivers Video/Audio/Camera Wi-Fi/BLE/LTE Routers - OPenWRT 	 IOT Platform Edge Processing Web & App Dashboard REST API MEAN Development
Security	Secure BootTPM	 Secure boot TPM SSL / SSH Encrypted Disc 	HTTPSSecure MQTTSSL User login



PCB Design Capabilities



PCB Design Capabilities

- Schematics Entry
- Library Development : Schematic Symbol / PCB Footprint / 3D Model
- Layout Design
- SI / PI / EMI Analysis / Thermal Analysis
- High Speed Digital / Analog and Mixed Signal / RF Designs
- High Voltage / High Current / Power Electronics
- Solid Expertise in Compliance standards IPC, UL / FCC / IEC / BIS



PCB Tools Expertise

- PCB Layout Cadence Allegro / Altium / Mentor PADS / Expedition
- Schematic Entry OrCAD Capture / Altium / Concept HDL / PADS Logic
- Signal Integrity / Power Integrity Sigrity / ADS / HFSS
- Thermal Analysis FloTHERM / Icepak / Solidworks
- CAM CAM 350 / Genesis / Valor Enterprise 3000

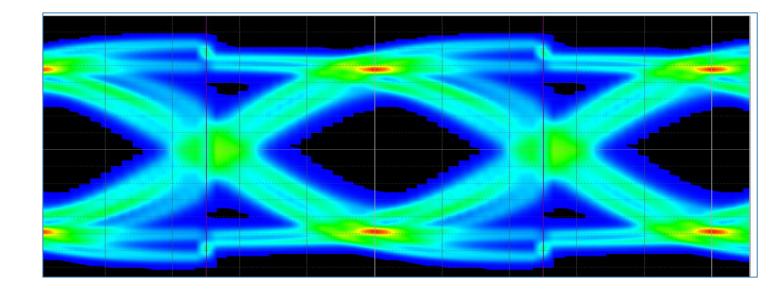


PCB Analysis Capabilities Signal Integrity / Power Integrity / Thermal



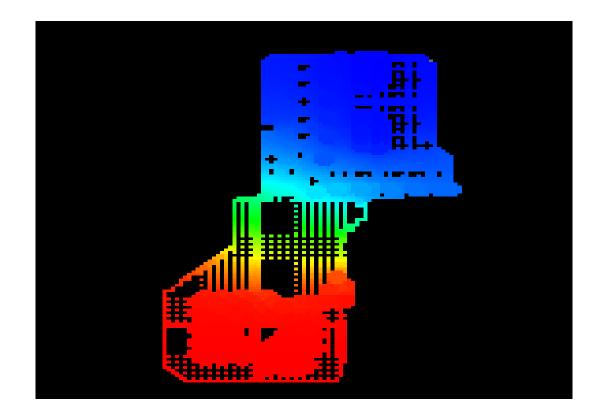
Signal Integrity Analysis

- Pre layout & Post layout SI Analysis
- Stack-up Analysis / Optimization
- Trace Impedance Analysis
- Via Optimization
- S-Parameter Extraction
- Crosstalk Analysis
- Co-design (IC/Package/Board)
- IBIS/IBIS-AMI Based System Simulation
- High Speed Serdes Simulations
- DDR / Parallel Bus simulations
- Eye Diagram Analysis
- Timing analysis.
- Connector/Socket/Needle Modeling



Power Integrity Analysis

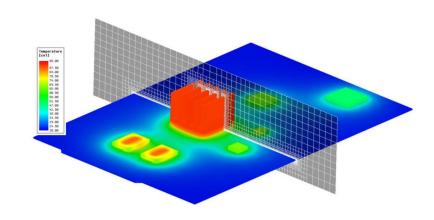
- DC IR Drop Analysis
- Power Via Current Analysis
- Plane Current Density Analysis
- PDN Power Impedance Analysis (Z11)
- Decoupling Capacitor Optimization
- Power Plane Resistance, Inductance and Capacitance Analysis
- Transient Noise Analysis.
- Time domain analysis with Current Profile and Voltage regulator models.
- Co-Simulation (Package/Board)





Thermal Analysis

- Complete solution through the design phase
- Chip Level / Board Level / Multi-board / System Level
- JEDEC standards compliance
- Thermal Analysis and Solutions offered:



Chip Level	Board Level	System Level
• Determination of Thermal Values - 0jc, 0jb	Determination of Hotspots, Thermal flow, Tj	Provide recommendations for Enclosure
Optimize Copper structure in substrateProvide recommendations for PCB Design	 Optimize placement for better Thermal dissipation & Reliability 	Design & ModificationsDetermine Vents Required
Extract and Design Simplified Thermal	Optimize via placements for better	Evaluate Heat spreading and recommend
model for further usage (2-R Compact /	conductivity	for Forced air cooling and design
DELPHI models)	Selection of materials, heatsinks, TIMDetailed Thermal simulations across	 Design Thermally enhanced designs - Board & System Combined
	different ambient conditions	Multi board modules



Simulation Tools Expertise

ANSYS

- Slwave
- Electronics Desktop Designer
- Electronics Desktop Circuit
- HFSS
- Q3D
- Icepak

Siemens

- Hyperlynx SI
- Hyperlynx PI
- Flotherm

Keysight ADS

- Channel Analysis
- Parallel Bus (DDR) Analysis

Cadence Sigrity

- PowerSI
- Clarity 3D
- PowerDC
- OptimizePI
- SystemSI



Mechanical & Industrial Design Capabilities



Mechanical Design Services

- Plastic Enclosure Design for Electronics
- Machined Aluminium / Sheet Metal / Extruded Enclosures
- Rugged Metal Enclosures for Military Application MIL-STD-810 / JSS55555
- IP Rated Enclosures IP65 / IP 67 / IP68
- Full Mechanical Systems Design
- DFx Manufacturability / Cost / Assembly / Compliance
- Thermal Analysis / Structural Design and Analysis Vibration / Impact / Drop



Industrial Design Services

- Design Research
- Product Story and Sketches / Product Visualization
- CAD and 3D Modelling
- UI & UX design
- Photorealistic Images / Photorealistic Product Animation Videos
- Rapid Prototyping CNC / FDM / SLA / SLS / Vacuum Casting



FPGA Capabilities

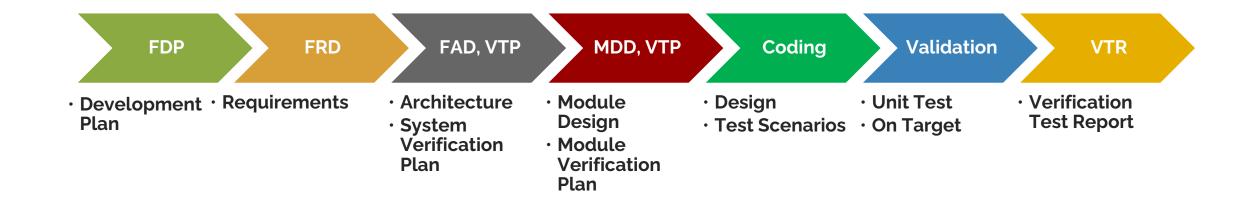


FPGA Design Services

- FPGA Design and Development
- FPGA Prototyping and Testing
- Custom IP Core Development
- FPGA-based System Integration
- Migration and Optimization Services
- Combined experience of over 30+ years in FPGA Design
- Cross Domain Experience Telecommunications / Automotive / Aerospace / Industrial Automation / Consumer Electronics / Medical Devices



FPGA Design Process Flow



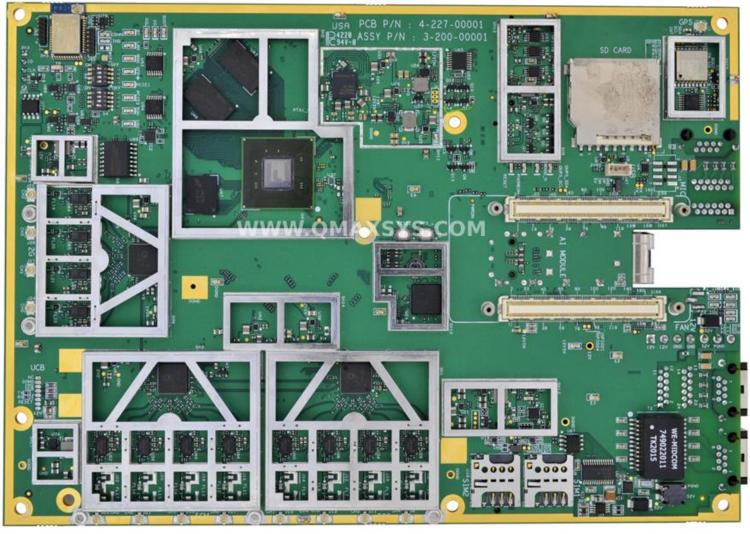
Product Design Case Studies



11ax Wireless AP - HW Spec

- Qualcomm IPQ8078A SoC
- 8x8 on 5Ghz and 4x4 on 2.4GHz
- MU MIMO / BLE / SFP+ / GigE
- LTE / GPS / POE / USB / PCIe
- Thermal / SI / PI Analysis
- High Density BGA Packages







Aerospace Structural Health Monitoring System

- Al enabled Air Frame Structural Analysis
- Altera A10 FPGA
- Digital Signal processing
- Low Power, Light Weight, Compact Design
- Complete HW / FPGA / Enclosure design
- Ultra-Low Noise / SNR of 50dB
- High Speed ADCs / DACs / Sync E / HV Mux

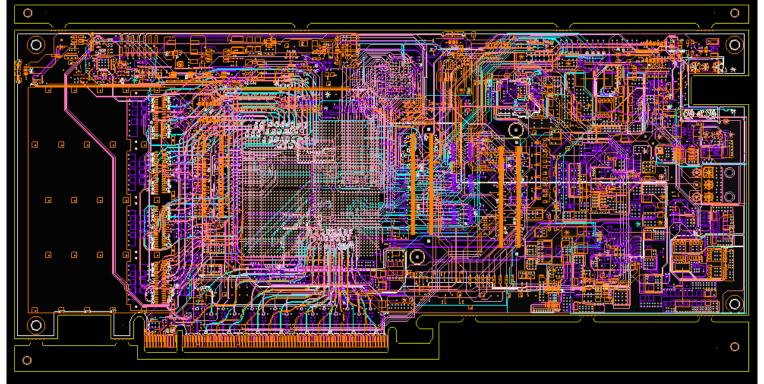




FPGA based 4 x 100G Interface Card

- Virtex® UltraScale+ FPGA
- Networking Application
- PCIe Gen 5 to QSFP+ x 4
- 1mm Pitch 2104 pin BGA
- High Density
- High Speed
- 16 Layer PCB
- HDI PCB







Rugged RF Power Supply

- Plasma Generation Application
- NXP i.MX6UL CPU
- NXP MRFE6VP61K25HR6 Rugged RF Power LDMOS Transistors
- Frequency: 13.56 MHz
- Rated Power: 1kW
- RJ45 / DB25 Communication Ports
- Customized RF Design
- Full Product Development and Delivery





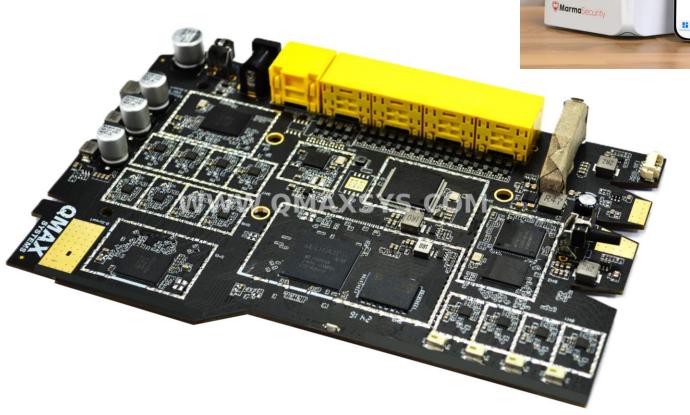
Connected On-board Diagnostic Device

- Full Product Development HW / FW / PCB / ID
- ARM Cortex A7 CPU / 1 Gb DDR3 / 4Gb eMMC
- Linux / Over the Air Firmware update (OTAP)
- Wi-Fi / BLE 4.1 / LTE-M / GPS / LCD Display
- Native CAN / Ethernet / USB 2.0
- Accelerometer / Magnetometer / LEDS
- 2000mAh Battery / Wireless Charging
- IP 65 Rated ABS Enclosure
- Deployed in GM Garages across USA



Cybersecurity Device

- MediaTek MT7986AV Wi-Fi 6/6E Router SoC
- Tri-band Wi-Fi: 4x4 -2.4GHz + 4x4 5GHz + 4x4 5.8GHz
- MU MIMO / BLE / DDR4 / GigE Ports / USB 3.0
- High Density BGA Packages
- Commercial Application
- Full Product Development
- Thermal / SI / PI Analysis
- RF Tuning / RF Calibration
- Prototyping and Testing
- FCC Certification
- Volume Production





Digital Signage with HDMI Input

- Full Product Development HW / FW / PCB / ID
- Rockchip 3568 Chipset
- HDMI Input HDCP compliant
- POE / 4K HDMI Output / 0.96" OLED Display
- Wi-Fi / Bluetooth / Gigabit Ethernet
- 4GB DDR4 RAM / 16GB eMMC
- USB 2.0 / 3.0
- RTC / IR Remote / Extender
- GPIOs / Audio OUT / Status LED





Mixed Reality / Image Processing

- Zynq® UltraScale+ FPGA
- Medical mixed reality application
- Image Processing Application
- HW Design / FW Development / FPGA SW





Hip Pack Board With Camera Module





Security System Controller

- Hardware / Firmware design and Development
- IMx6 CPU / STM32 ARM Cortex-M Controller
- Linux / RTOS / Ethernet / DIO / AIO / PoE
- Mechanical / Enclosure Design / DFM
- FCC Class B certified
- BGA ICs / Local Assembly



Stackable Design





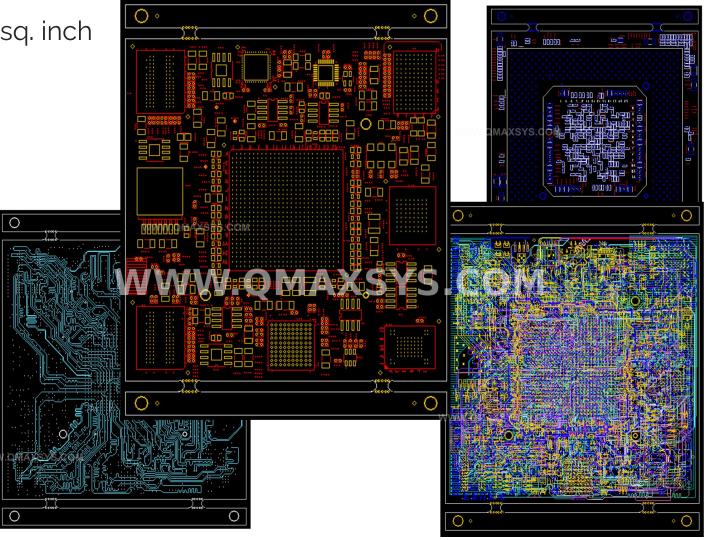


PCB Design Case Studies



Rugged SBC Board

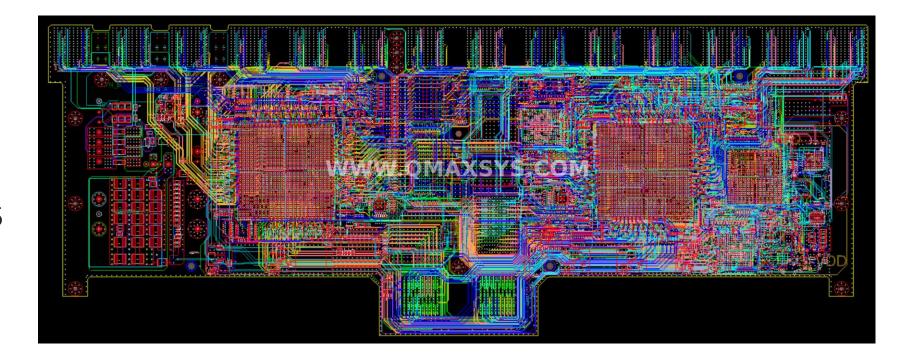
- Ultra high density 460 Pins per sq. inch
- Military Application
- 20 layer
- High Speed Digital
- Double side components
- HDI Blind / Buried Vias





Networking Board

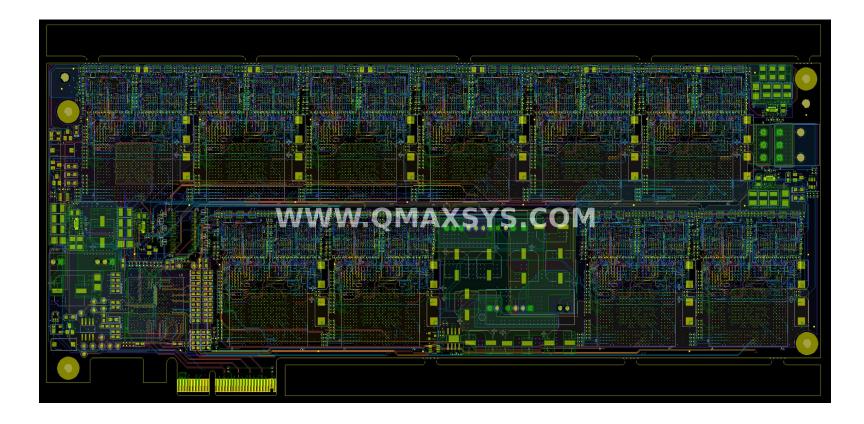
- 100 GBE Switch/Router Board / High speed / DDR3
- 36 layers / 2597 Pins BGAs
- 19705 pins
- Chipset: BCM88650
- High Current
- Ultrahigh density
- Cadence Allegro 16.5





Video Processor PCB

- Video Processing Hardware
- High speed digital / PCIE / DDR3
- Cadence Allegro
- High Current
- Total pin count : 16533





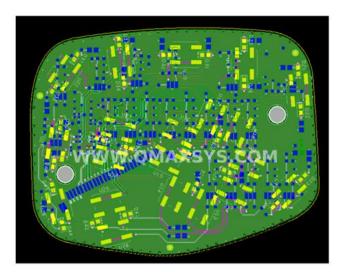
Automotive PCBs





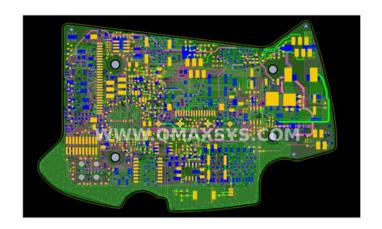














Industrial Design Case Studies



Case Studies

















Case Studies



















Thanks!

Saravana

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